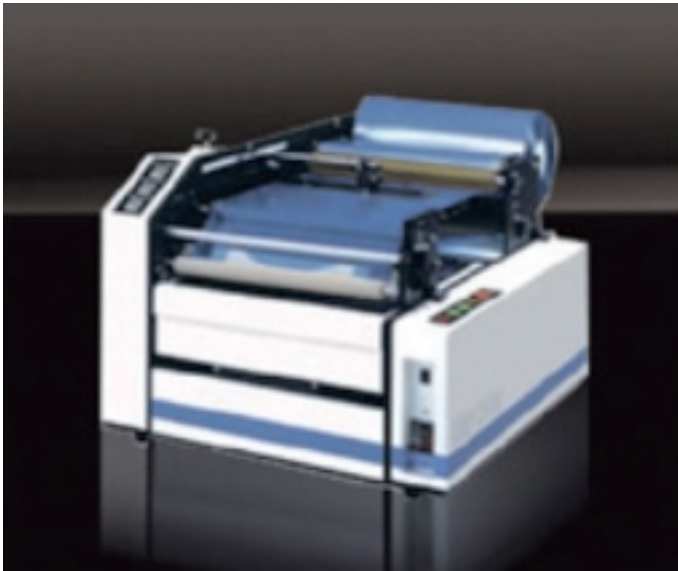


200mm Semi-Automatic Wafer Mounter

# RAD-2500m/8



## Outline

-Semi-automatic wafer mounter that mounts wafer onto the pre-cut dicing tape once the operator supplies the wafer and ring frame by hand.

### Options

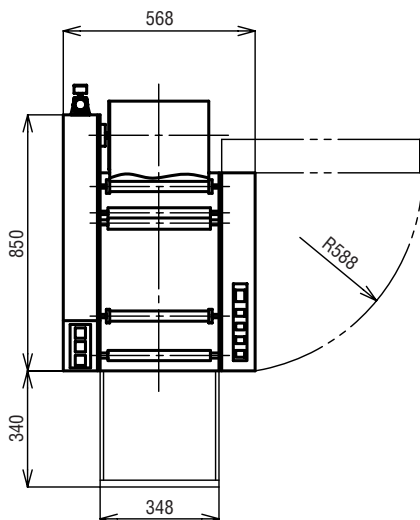
- Static Eliminator
- Top Cover
- Wafer Positioning Pins

### Suitable Tapes

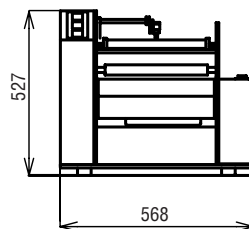
- Pre-cut dicing tape : Adwill D series, G series
- Dicing die bonding tape : Adwill LE Tape

## External View

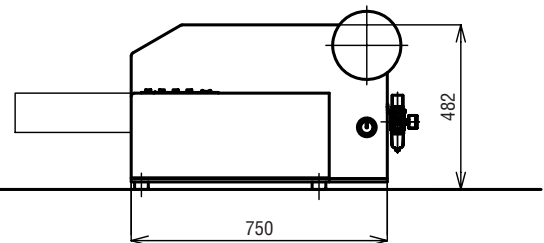
Unit:mm



Top View



Front View



Right Side View

## Facility

<b>Power Supply</b>	Voltage	: AC100V (±10%)
	Frequency	: 50/60Hz
	Phase	: single phase
<b>Air Supply</b>	Power consumption	: 0.2KVA
	Air pressure	: 0.5-0.8MPa
	Air consumption	: <150L/min (ANR)

## Applicable Wafer Size

200mm  
Additional compatibility with various wafer sizes and shapes are available as an option. Please feel free to inquire.

## Size

Width : 568mm  
Depth : 850mm  
(with table fully advanced : Max.1,190mm)  
Height : 527mm

## Weight

90kg

## Processing Capacity

18sec/wafer (excludes setting time)



**LINTEC Corporation** *Linking your dreams*

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